

SOD95

plastic single-ended package; low-profile 2-lead TO-220

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	TO-220
Package type industry code	TO-220
Package style descriptive code	SIP (single in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	low-profile 2-lead TO-220
Mounting method type	T (through-hole mount)
Issue date	13-9-1999

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		10	-	10.5	11	mm
E	package width		9.7	-	10	10.3	mm
A	seated height		[tbd]	-	14	14	mm
A ₂	package height		4.1	-	4.3	4.5	mm
n ₂	actual quantity of termination		-	-	2	-	



2. Package outline

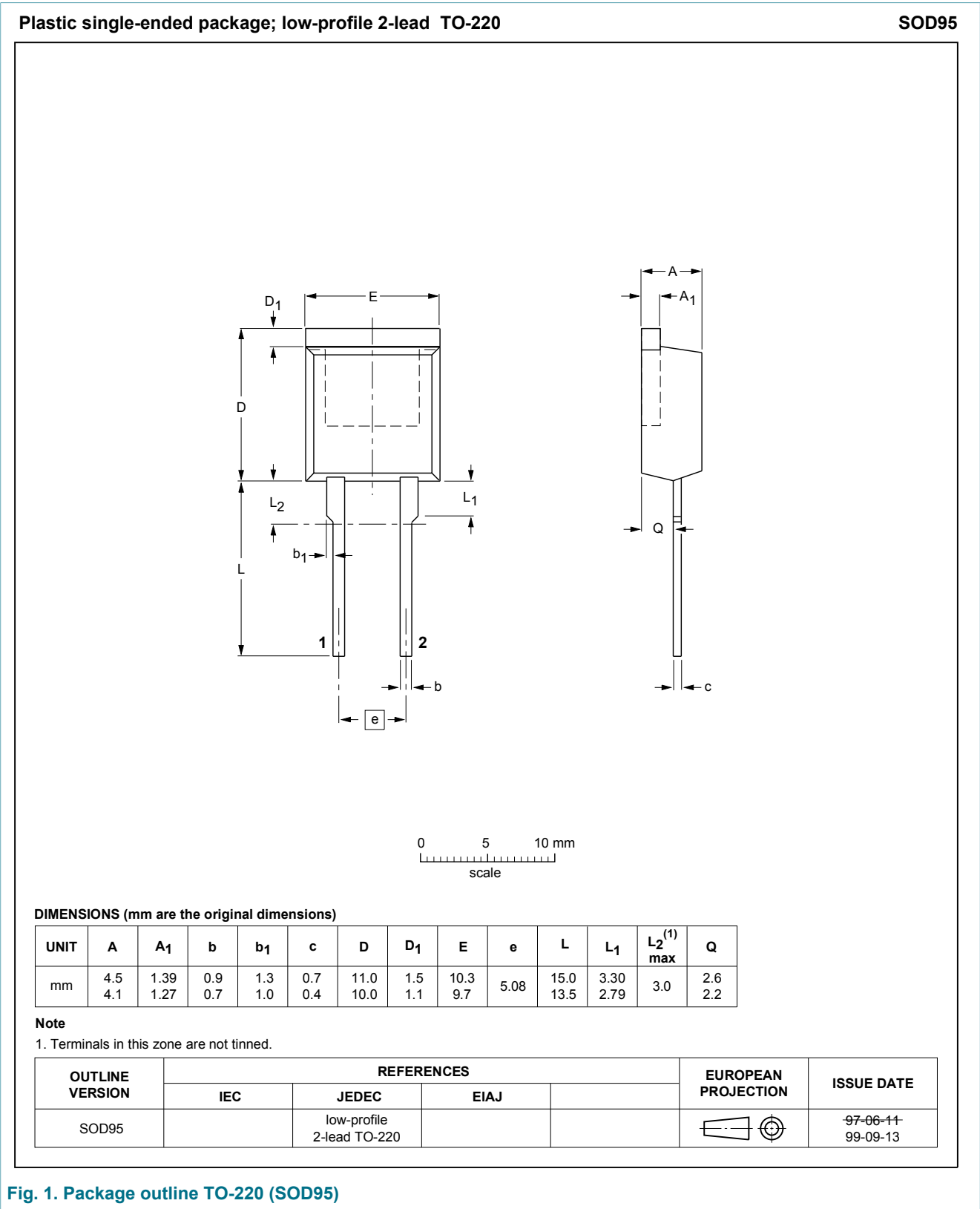


Fig. 1. Package outline TO-220 (SOD95)

3. Legal information

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4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 3

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